

09/24/2001

ABSTRACT

- 5 A microelectronic device includes a microelectronic die having an interfacial metal layer deposited over an active surface thereof to perform a signal distribution function within the device. The microelectronic die is fixed within a package core to form a die/core assembly. One or more metallization layers may then be built up over the die/core assembly as part of a packaging scheme. The interfacial metal layer can be applied either before or after the die is fixed within the package core. In one approach, the interfacial layer is applied during wafer-level processing.

09/24/2001 04:30:01

"Express Mail" mailing label number: EL721274239US

Date of Deposit: April 30, 2001

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